

LCD Module Product Specification

64128K FC BW-RGB

128 x 64 DOTS Monochrome Display with RGB Backlight

June 8, 2018

Remark:

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Revision Record

REV	CHANGES	DATE
A0 (Ref. A00	First release	Apr 7, 2017
20170407)		
A1 (Ref. A01 20180529)	Updated backlight pins location tolerance in section 2. Mechanical Drawing.	Jun 8, 2018
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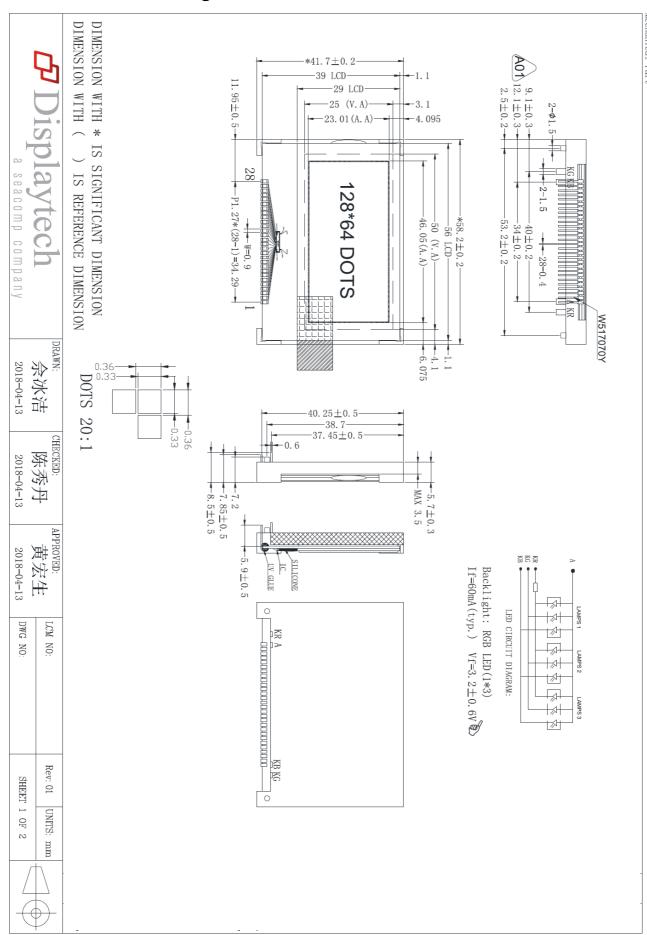
Table of Content

Re	evision Record	1
1.	General Specifications	3
2.	Mechanical Drawing	4
3.	Interface I/O Terminal	5
	3.1 Pin Description	6
4.	Electro-Optical Specifications	6
	4.1 Absolute Maximum Ratings	6
	4.2 Optical Characteristics	
	4.3 Electrical Characteristics	7
	4.4 Timing Characteristics	8
5.	Programming	13
	5.1 Instruction Table	13
	5.2 Display Data RAM	14
Αŗ	opendix A	15
	A.1 Packing Method	15
	A.2 Part Number Definition	16
	A.3 Definitions of Optical Characteristic	16
Αŗ	opendix B	19
	B.1 Quality Units	19
	B.2 Reliability Test	23
	B.3 Caution for Using	23

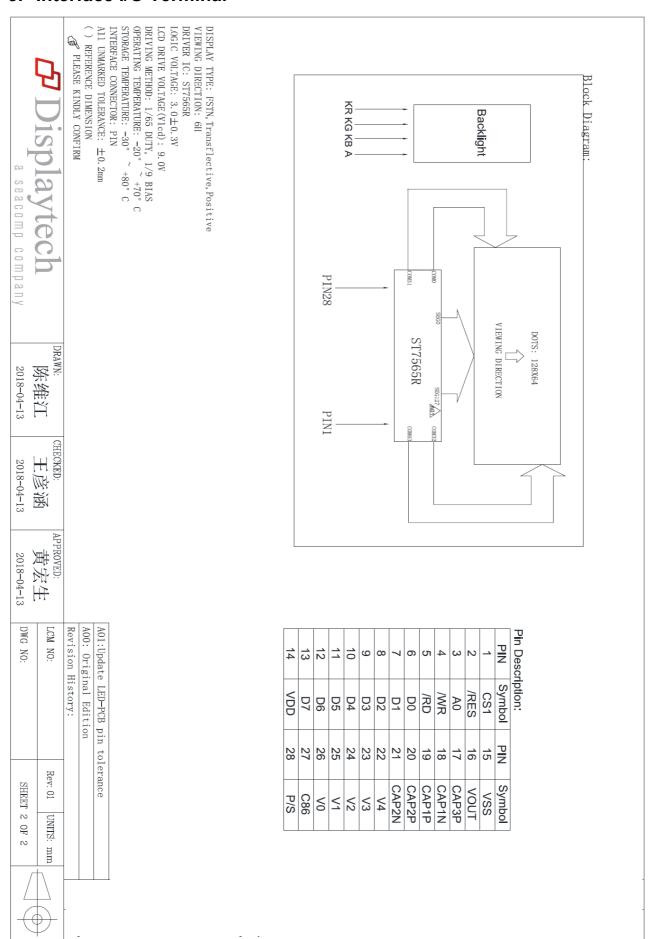
1. General Specifications

Item	Standard Value	Unit
Display Pattern	Graphic	
Color	Mono	
Resolution	128 x 64	DOTS
Module Dimension (W x H x T)	58.2 x 41.7 x 5.7	mm
Viewing Area (W x H)	50 x 25	mm
Active Area (W x H)	46.05 x 23.01	mm
DOT Size (W x H)	0.33 x 0.33	mm
DOT Pitch (W x H)	0.36 x 0.36	mm
LCD Type	FSTN, Positive	
Polarizer Type	Transflective	
View Direction	6 H	
LCD Controller & Driver	ST7565R	
LCD Driving Method	1/65 duty,1/9 bias	
Interface Type	4-line SPI; Parallel 6800, 8080	
Backlight Type	LED	
Backlight Color	RGB	
DC-DC Converter	Build-in	
Operation Temperature	-20 ~ +70	°C
Storage Temperature	-30 ~ +80	°C

2. Mechanical Drawing



3. Interface I/O Terminal



3.1 Pin Description

Pin	Symbol	Function Description
1	CS1	Chip select (Active low)
2	/RES	Reset input (Active low)
3	A0	Command/data select
4	/WR	Write execution control pin
5	/RD	Read execution control pin
6	D0	Bi-directional data
7	D1	Bi-directional data
8	D2	Bi-directional data
9	D3	Bi-directional data
10	D4	Bi-directional data
11	D5	Bi-directional data
12	D6	Bi-directional data
13	D7	Bi-directional data
14	VDD	Power supply
15	VSS	Power ground
16	VOUT	DC/DC voltage converter
17	CAP3P	DC/DC voltage converter
18	CAP1N	DC/DC voltage converter
19	CAP1P	DC/DC voltage converter
20	CAP2P	DC/DC voltage converter
21	CAP2N	DC/DC voltage converter
22	V4	Power supply for LCD
23	V3	Power supply for LCD
24	V2	Power supply for LCD
25	V1	Power supply for LCD
26	V0	Power supply for LCD
27	C86	MPU interface select
28	P/S	Parallel mode/serial mode select

4. Electro-Optical Specifications

4.1 Absolute Maximum Ratings

No	Item	Symbol	Min	Max	Unit
1	Power Supply Voltage	VDD	-0.3	3.6	V
2	Power Supply Voltage (VDD standard)	V0, VOUT	-0.3	13.5	V
3	Power Supply Voltage (VDD standard)	V1, V2, V3, V4	-0.3	V0	V

Note: Operating Temperature and Storage Temperature can be found in 1. General Specifications.

4.2 Optical Characteristics

No	Item		Symbol	Condition	Min	Тур	Max	Unit
1	Contrast Ratio		Cr	Ta=23±3°C VLCD = Typ. (2)	-	4.3	ı	-
2	Response Tim	20	Tr	Ta=23±3°C	-	150	230	ms
	Response IIII	nse time Tf		1a-23±3 C	-	230	315	ms
3	Viewing Angle	3H		Cr = 2 Ta=23±3°C	22	28	1	Deg
		9H			43	42	1	Deg
3		6H			37	40	-	Deg
		12H			38	40	-	Deg
	R Brightness				-	55	-	cd/m²
4	G Brightness		Lv	Ta=23±3°C	-	130	-	cd/m²
	B Brightness			ILED = Typ.	-	22	-	cd/m²
5	Luminance Ur	niformity	∆Lv		75	-	-	%

- (1) See Appendix Definition of Optical Characteristics for detail.(2) VLCD can be found in 4.3 Electrical Characteristics.

4.3 Electrical Characteristics

No	Item	Symbol	Condition	Min	Тур	Max	Unit
1	Power Supply Voltage	VDD	-	2.7	3.0	3.3	V
2	Power Supply Voltage (LCD drive voltage)	V0 (V _{LCD})	Ta=23±3°C	8.6	8.8	9.0	V
3	Current consumption for LCD	ldd	-	-	0.5	1.5	mA
4	Input High-level Voltage	V _I H	-	0.8*VDD		VDD	V
5	Input Low-level Voltage	V _{IL}	-	VSS		0.7*VDD	V
6	Output High-level Voltage	V _{OH}	-	0.8*VDD		VDD	V
7	Output Low-level Voltage	V _{OL}	-	VSS		0.2*VDD	V
8	Forward Current of Backlight	lf	Ta=23±3°C		60		mA
9	Forward Voltage of Backlight	Vf		2.6	3.2	3.8	V
10	Luminous Uniformity of Backlight	△Lv	16_ T	75	-	-	%
		R	lf= Typ. Ta=23±3°C	620		635	-
11	Emission Wavelength	G	14 20:0	510		535	-
		В		460		480	-

4.4 Timing Characteristics

System Bus Read/Write Characteristics 1 (For the 8080 Series MPU)

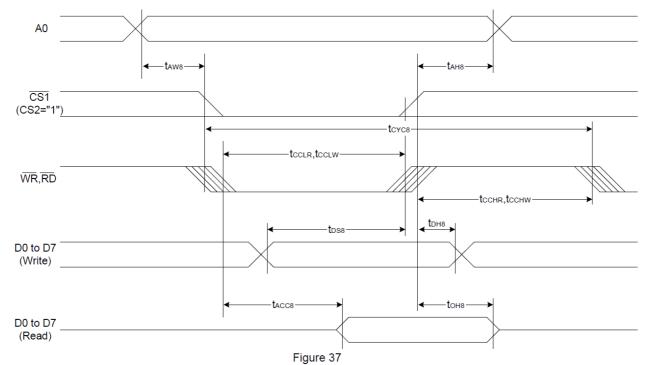


Table 24

(VDD = 3.3V, Ta = -30 to 85℃)

Itam	Signal	Sumbol	Condition	Rating		Units
ltem	Signal	Symbol	Condition	Min.	Max.	Units
Address hold time		taн8		0	_	
Address setup time	A0	taw8		0	_	
System cycle time]	tcyc8		240	_	
Enable L pulse width (WRITE)	WR	tccLW		80	_	
Enable H pulse width (WRITE)	T VVK	tccнw		80	_]
Enable L pulse width (READ)	- RD	tcclr		140	_	Ns
Enable H pulse width (READ)		tcchr		80		
WRITE Data setup time		tDS8		40	_	
WRITE Address hold time	D0 to D7	tонв		0	_	
READ access time	7 00 10 07	tacc8	CL = 100 pF	_	70]
READ Output disable time]	tонв	CL = 100 pF	5	50]

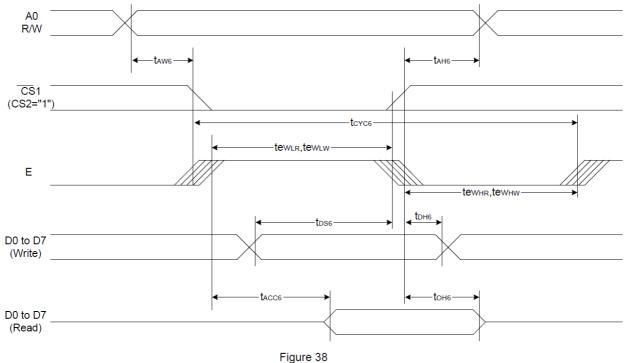
Table 25

(VDD = 2.7V, Ta = -30 to 85%)

ltem	Cianal	Sumbol	Condition	Rating		Units
item	Signal	Symbol	Condition	Min.	Max.	Units
Address hold time		taн8		0	_	
Address setup time	A0	taw8		0	_	
System cycle time		tcyc8		400	_	
Enable L pulse width (WRITE)	WR	tccLw		220		
Enable H pulse width (WRITE)	WK	tсснw		180	_	
Enable L pulse width (READ)	RD	tcclr		220	_	ns
Enable H pulse width (READ)	ND.	tcchr		180	_	
WRITE Data setup time		tDS8		40	_	
WRITE Address hold time	D0 to D7	tон8		0	_	
READ access time	00 10 07	tacc8	CL = 100 pF	_	140	
READ Output disable time		tонв	CL = 100 pF	10	100	

^{*1} The input signal rise time and fall time (tr, tr) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \le (t_{CYC8} - t_{CCLW} - t_{CCHW})$ for $(t_r + t_f) \le (t_{CYC8} - t_{CCLR} - t_{CCHR})$ are specified.

System Bus Read/Write Characteristics 2 (For the 6800 Series MPU)



^{*2} All timing is specified using 20% and 80% of VDD as the reference.

^{*3} tccLw and tccLR are specified as the overlap between /CS1 being "L" (CS2 = "H") and /WR and /RD being at the "L" level.

Table 26

(VDD = 3.3V, Ta = -30 to 85%)

ltem	Signal	Symbol	Condition	Rati	ing	Units
item	Signal	Syllibol	Min. Max.		Units	
Address hold time		tah6		0	_	
Address setup time	A0	taw6		0	_	
System cycle time		tcyc6		240	_	
Enable L pulse width (WRITE)	WR	tewlw		80	_	
Enable H pulse width (WRITE)] VVIX	tewnw		80	_	
Enable L pulse width (READ)	RD	tewlr		80	_	ns
Enable H pulse width (READ)	, KD	tewhr		140		
WRITE Data setup time		tDS6		40	_	
WRITE Address hold time	D0 to D7	tDH6		0	_	
READ access time		tacc6	CL = 100 pF	_	70	
READ Output disable time		tоне	CL = 100 pF	5	50	

Table 27

(VDD = 2.7V, Ta = -30 to 85%)

lta.m.	Cimnal	Sumb of	Condition	Rati	ing	I Inita
ltem	Signal	Symbol	Condition	Min.	Max.	Units
Address hold time		tah6		0	_	
Address setup time	A0	taw6		0	_	
System cycle time		tcyc6		400	_	
Enable L pulse width (WRITE)	WR	tewlw		220	_	
Enable H pulse width (WRITE)	VVIX	tewnw		180	_	
Enable L pulse width (READ)	RD	tewlr		220	_	ns
Enable H pulse width (READ)	I ND	tewhr		180	_	
WRITE Data setup time		tDS6		40	_	
WRITE Address hold time	D0 to D7	tDH6		0	_	
READ access time	ן טטוטטי	tacc6	CL = 100 pF	_	140	
READ Output disable time]	toн6	CL = 100 pF	10	100	

^{*1} The input signal rise time and fall time (t_r, t_f) is specified at 15 ns or less. When the system cycle time is extremely fast, $(t_r + t_f) \le (t_{CYC6} - t_{EWLW} - t_{EWHW})$ for $(t_r + t_f) \le (t_{CYC6} - t_{EWLR} - t_{EWHR})$ are specified.

^{*2} All timing is specified using 20% and 80% of VDD as the reference.

^{*3} tewlw and tewlr are specified as the overlap between $\overline{\text{CS1}}$ being "L" (CS2 = "H") and E.

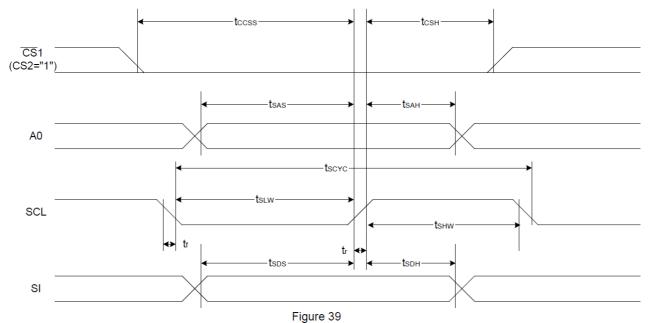


Table 28

(VDD = 3.3V,Ta = -30 to 85℃)

Item	Signal	Symbol	Condition	Rating		Units
	Signal	Symbol	Condition	Min.	Max.	Ullits
4-line SPI Clock Period		Tscyc		50	_	
SCL "H" pulse width	SCL	Tshw		25	_	
SCL "L" pulse width		TsLW		25	_	
Address setup time	A0	Tsas		20	_]
Address hold time	Au	Tsah		10	_	ns
Data setup time	SI	Tsds		20	_	
Data hold time	31	Тѕрн		10	_	
CS-SCL time	CS	Tcss		20	_	1
CS-SCL time		Tcsh		40	_	

Table 29

(VDD = 2.7V, Ta = -30 to 85%)

14	6:	Complete L	C	Rat	11	
Item	Signal	Symbol	Condition	Min.	Max.	Units
4-line SPI Clock Period		Tscyc		100	_	
SCL "H" pulse width	SCL	Tshw		50	_	
SCL "L" pulse width		Tslw		50	_	
Address setup time	A0	Tsas		30	_	
Address hold time	Au	Тѕан		20	_	ns
Data setup time	SI	Tsds		30	_	
Data hold time	31	Тѕон		20	_	
CS-SCL time	cs	Tcss		30	_	
CS-SCL time		Тсѕн		60	_]

 $^{^{\}ast}1$ The input signal rise and fall time (tr, tf) are specified at 15 ns or less. $^{\ast}2$ All timing is specified using 20% and 80% of VDD as the standard.

Reset Timing

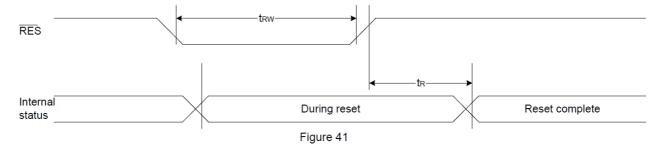


Table 30

 $(VDD = 3.3V, Ta = -30 \text{ to } 85^{\circ}C)$

Itom	Signal	Symbol	Condition	,	Rating		Units
Item	Signai	Symbol	mboi Condition		Тур.	Max.	Units
Reset time		tr		_	_	1.0	us
Reset "L" pulse width	/RES	trw		1.0	_	_	us

Table 31

 $(VDD = 2.7V, Ta = -30 \text{ to } 85^{\circ}C)$

Item	Signal	Symbol	Condition	Ì	Rating		Units
Item	Signal	Symbol	Condition	Min.	Тур.	Max.	Units
Reset time		tr		_	_	2.0	us
Reset "L" pulse width	/RES	trw		2.0	_	_	us

 $^{^{\}ast}1$ All timing is specified with 20% and 80% of VDD as the standard.

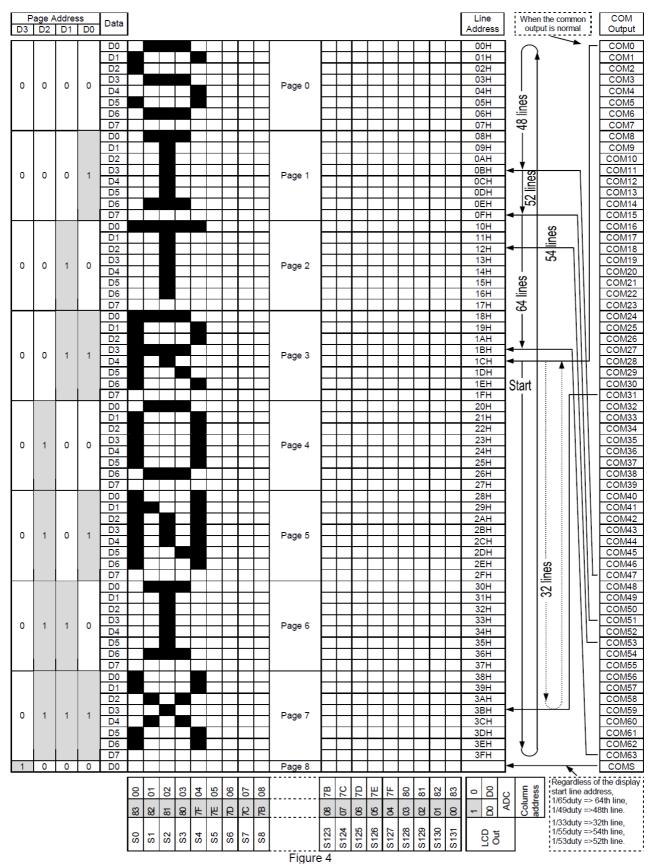
5. Programming

5.1 Instruction Table

			Т						65R	Com	mand	(Note) *: ignored data
Command	Α0	/RD	/WR	D7	D6		D4		D2	D1	D0	Function
(1) Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0	LCD display ON/OFF 0: OFF, 1: ON
(2) Display start line set	0	1	0	0	1		Disp	lay st	art a	ddres	ss	Sets the display RAM display start line address
(3) Page address set	0	1	0	1	0	1	1	Р	age	addre	ess	Sets the display RAM page address
(4) Column address set upper bit Column address set lower bit	0	1	0	0	0	0	1	co Le	lumn ast s	ignifid addı ignifid addı	ress cant	Sets the most significant 4 bits of the display RAM column address. Sets the least significant 4 bits of the display RAM column address.
(5) Status read	0	0	1		Sta	itus		0	0	0	0	Reads the status data
(6) Display data write	1	1	0					W	rite d	ata		Writes to the display RAM
(7) Display data read	1	0	1					Re	ad d	ata		Reads from the display RAM
(8) ADC select	0	1	0	1	0	1	0	0	0	0	0	Sets the display RAM address SEG output correspondence 0: normal, 1: reverse
(9) Display normal/ reverse	0	1	0	1	0	1	0	0	1	1	0	Sets the LCD display normal/ reverse 0: normal, 1: reverse
(10) Display all points ON/OFF	0	1	0	1	0	1	0	0	1	0	0	Display all points 0: normal display 1: all points ON
(11) LCD bias set	0	1	0	1	0	1	0	0	0	1	0	Sets the LCD drive voltage bias ratio 0: 1/9 bias, 1: 1/7 bias (ST7565R)
(12) Read-modify-write	0	1	0	1	1	1	0	0	0	0	0	Column address increment At write: +1 At read: 0
(13) End	0	1	0	1	1	1	0	1	1	1	0	Clear read/modify/write
(14) Reset	0	1	0	1	1	1	0	0	0	1	0	Internal reset
(15) Common output mode select	0	1	0	1	1	0	0	0	*	*	*	Select COM output scan direction 0: normal direction 1: reverse direction
(16) Power control set	0	1	0	0	0	1	0	1	0	perat mod		Select internal power supply operating mode
(17) V ₀ voltage regulator internal resistor ratio set	0	1	0	0	0	1	0	0	Res	sistor	ratio	Select internal resistor ratio(Rb/Ra) mode
(18) Electronic volume mode set Electronic volume	0	1	0	1	0	0	0	0	0	0	1	Set the V ₀ output voltage
register set				0	0	E	lectro	onic v	/olun	ne va	lue	electronic volume register
			,	1	0	1	0	1	1	0	0	0: Sleep mode, 1: Normal mode
(19) Sleep mode set	0	1	0	*	*	*	*	*	*	0	1 0	
(00) Baar (•		_	1	1	1	1	1	0	0	0	select booster ratio 00: 2x,3x,4x
(20) Booster ratio set	0	1	0	0	0	0	0	0	0		p-up ilue	01: 5x 11: 6x
(21) NOP	0	1	0	1	1	1	0	0	0	1	1	Command for non-operation
(22) Test	0	1	0	1	1	1	1	*	*	*	*	Command for IC test. Do not use this command

Note: See Datasheet of LCD Driver for detail.

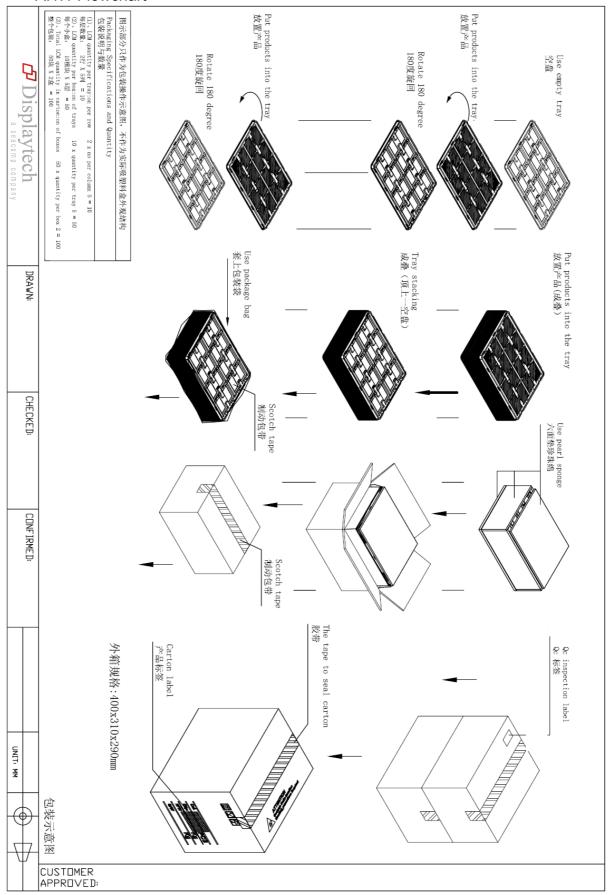
5.2 Display Data RAM



Appendix A

A.1 Packing Method

A.1.1 Flowchart



Note: Detail refer to goods label in mass production

A.1.2 Carton Label

Carton label is printed with A4 paper.

PART NO: 64128K FC BW-RGB

QTY: 100 PCS

P/O NO: XXXXXXXXX

CARTON: TBD

DISPLAYTECH

UNIT E, 31/F, BILLION PLAZA 2 10 CHEUNG YUE STREET

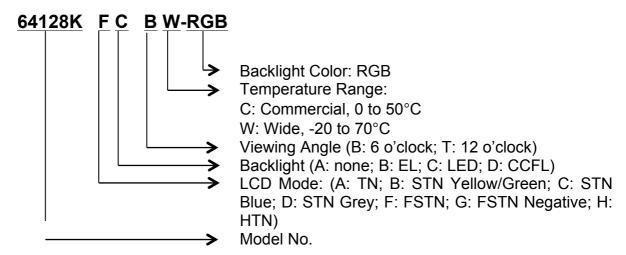
CHEUNG SHA WAN, KLN, HONG KONG

TEL: +852 2311 2080 FAX: +852 2722 6998 MADE IN CHINA

Remark:

- 1) PART NO = Displaytech part number
- 2) QTY = Quantity of products inside the box
- 3) P/O NO = Customer PO number
- 4) CARTON = Carton number

A.2 Part Number Definition



A.3 Definitions of Optical Characteristic

A.3.1 Contrast Ratio Test

- A) Contrast ratio is calculated by the following formula when the output voltage is obtained from the electro-optical test system.
- B) Test Condition: Accord to the LCD's driving method and operating voltage (VLCD).
- C) Formula:

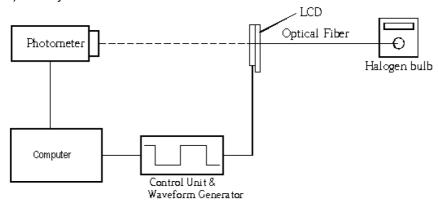
Contrast Ratio = Photometer output voltage when non-select waveform is applying

(Positive type) Photometer output voltage when select waveform is applying

Contrast Ratio = Photometer output voltage when select waveform is applying

(Negative type) Photometer output voltage when non-select waveform is applying

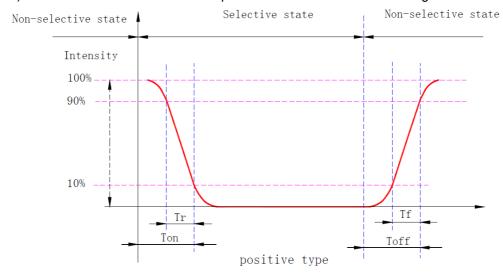
D) Test system:



A.3.2 Response time

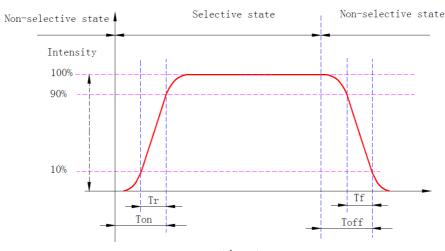
A.3.2.1 Positive type

- A) Rise time is defined as the time required for the transmission to change from 90% to 10%.
- B) Fall time is defined as the time required for the transmission to change from 10% to 90%.
- C) On time is defined as the time required for the transmission to change from 100% to 10%.
- D) Off time is defined as the time required for the transmission to change from 0% to 90%.



A.3.2.2 Negative type

- A) Rise time is defined as the time required for the transmission to change from 10% to 90%.
- B) Fall time is defined as the time required for the transmission to change from 90% to 10%.
- C) On time is defined as the time required for the transmission to change from 0% to 90%.
- D) Off time is defined as the time required for the transmission to change from 100% to 10%.



negative type

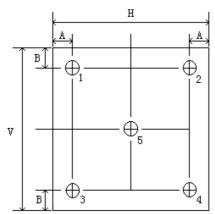
A.3.3 Luminance Measurement

Luminance is a cd/m² (nits) measurement of the display's white color (white screen).

All measurements are performed in a dark ambient.

Display luminance is defined as the average value of five (5) white screen measurements. The location of these 5 measurement points is shown in the drawing below.

Display Luminance = Surface Luminance of all white screen (1+2+3+4+5)



Screen Luminance Measurement Points (5)

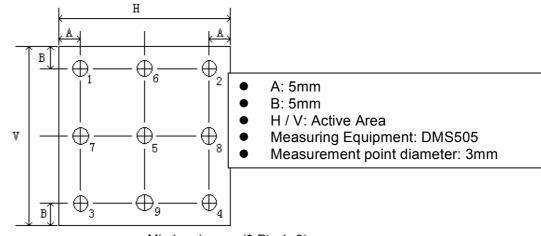
- A: 5mm
- B: 5mm
- H / V: Active Area
- Measuring Equipment: DMS505
- Measurement point diameter: 3mm

A.3.4 White Uniformity Measurement

White luminance uniformity is a cd/m² (nits) measurement of the display's white color across the display screen.

All measurements are performed in a dark ambient.

Display luminance uniformity is defined as the percent (%) of luminance value variation over nine (9) white screen measurements. The location of these 9 measurement points is shown in the drawing below.

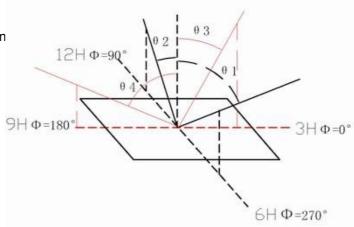


Luminance Uniformity = Min Luminance (9 Pts.1-9)

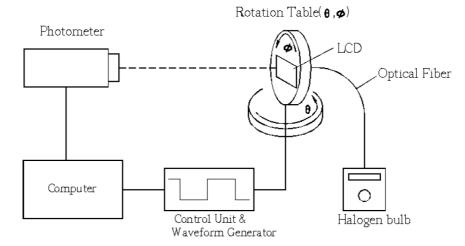
Max Luminance (9 Pts.1-9) x 100%

A.3.5 Viewing Angle

A) Viewing angle is definition



B) System Block Diagram



Appendix B

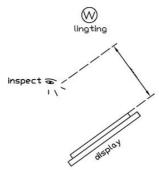
B.1 Quality Units

B.1.1 Purpose & Scope

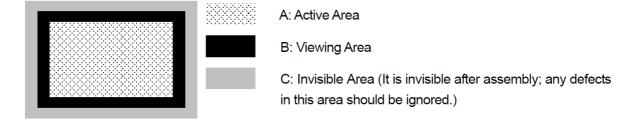
- a. This standard is applicable for mono STN products which were produced by our company. All mono STN products of our company should be subject to this standard;
- b. If some defect item was not defined exactly in this standard, there must be a negotiation between customer and our company;
- c. If customer had special requirements, there also must be a negotiation between customer and our company.

B.1.2 Inspection Conditions

- a. Inspection direction should be perpendicular to LCD surface;
- b. Inspection should be performed under the condition of 20~40W fluorescent lamp;
- c. The distance between inspector's eyes & product surface should be $30 \text{cm} \sim 50 \text{cm}$ when inspection.



B.1.3 Definition of LCD area



B..4 Sampling Plan

a. Sampling Method

According to GB2828.1-2003 (Equivalent to MIL-STD-105/E) General inspection level II.

b. AQL Definition

Major: AQL=0.65 (Please refer to the definition in "B.1.5 & B.1.6 Inspection Criteria") Minor: AQL=1.0 (Please refer to the definition in "B.1.5 & B.1.6 Inspection Criteria")

B.1.5 Inspection Criteria (Not energized)

No	Defect Name & Illustration		Criteria							Class
1.5.1	Light Leakage	Not allowed	Not allowed							
1.5.2	Vacuum Bubble	Not allowed	I							Major
1.5.3	Rainbow	According t	o limit sam	ple						Minor
1.5.4	Glass Crack	Not allowed	I							Minor
1.5.5	Protrusion - ITO lead	Y≤L/3, allow	Y > C L > ved quantit	y:2		← L	Y→ ← →			Minor
1.5.6	Protrusion – Edge	Allowed if p	Allowed if protrusion didn't affect dimension.						Minor	
1.5.7	Chip glass - ITO Lead	Unit: mm S (cm²) 50 <s 12<s≤50="" random="" remark:="" s="" s<="" s≤12="" td=""><td colspan="6">S (cm²) X Y Z Allowed Qty 50<s< td=""> ≤6.0 ≤L/3 ≤T 3 12<s≤50< td=""> ≤5.0 ≤L/3 ≤T 3 S≤12 ≤4.0 ≤L/3 ≤T 3</s≤50<></s<></td><td>3 3 3</td><td>Minor</td></s>	S (cm²) X Y Z Allowed Qty 50 <s< td=""> ≤6.0 ≤L/3 ≤T 3 12<s≤50< td=""> ≤5.0 ≤L/3 ≤T 3 S≤12 ≤4.0 ≤L/3 ≤T 3</s≤50<></s<>						3 3 3	Minor
1.5.8	Chip glass – Edge	Unit: mm S (cm2) 50 <s 12<s≤50="" random<="" s="" s≤12="" th=""><th>X ≤6.0 ≤5.0 ≤4.0 Random</th><th>Y* ≤2.0 ≤1.5 ≤1.0 ≤0.5</th><th>Z</th><th>Ext</th><th>tend widtl seal line ≤1/2 ≤1/2 ≤1/3</th><th>n of</th><th>Allowed Qty NC NC NC NC NC</th><th>Minor</th></s>	X ≤6.0 ≤5.0 ≤4.0 Random	Y* ≤2.0 ≤1.5 ≤1.0 ≤0.5	Z	Ext	tend widtl seal line ≤1/2 ≤1/2 ≤1/3	n of	Allowed Qty NC NC NC NC NC	Minor
1.5.9	Chip glass – Corner	Unit: mm S (cm²) 50 <s 12<s≤50="" 2<="" if="" remark:="" s≤12="" td=""><td colspan="2">Unit: mm S (cm²) X Y Z Allowed Qty 50<s< td=""> ≤6.0 ≤L ≤T 2 12<s≤50< td=""> ≤5.0 ≤L ≤T 2</s≤50<></s<></td><td>2 2 2</td><td>Minor</td></s>	Unit: mm S (cm²) X Y Z Allowed Qty 50 <s< td=""> ≤6.0 ≤L ≤T 2 12<s≤50< td=""> ≤5.0 ≤L ≤T 2</s≤50<></s<>		2 2 2	Minor				

Note (1): NC = Not Count

No	Defect Name & Illustration	Criteria										
		Suppose S (2)	Suppose S (2) = The area of A, the criteria in A&B is as below,									
	Circular type	S (cm ²) Φ (mm)	S≤4	4 <s≤12< td=""><td>12<s≤50< td=""><td>50<s≤150< td=""><td>S>150</td><td></td></s≤150<></td></s≤50<></td></s≤12<>	12 <s≤50< td=""><td>50<s≤150< td=""><td>S>150</td><td></td></s≤150<></td></s≤50<>	50 <s≤150< td=""><td>S>150</td><td></td></s≤150<>	S>150					
	←	Ф≤0.10	NC	NC	NC	NC	NC					
		0.10<Φ≤0.20	1	2	2	3	3					
1.5.10	\ \ \	0.20<Φ≤0.30	1	1	2	2	3	Minor				
		Ф>0.30	0	0	0	0	0					
	Φ= (a+b) / 2	Remark: Bubl should be reg Maximum def Please refer to Diagonal.	arded as ect numb o footma	circular doer in 1cm	efect. ² is 1. conversion	between S &	` &					
		Suppose S=		of A, the	criteria in a	kb is as belo	ΟW,					
	Linear type	S (c a&b Φ (mm)	^(;m²) S≤	≦4 4<\$≤′	12 <s≤50< td=""><td>50<s≤150< td=""><td>S>150</td><td></td></s≤150<></td></s≤50<>	50 <s≤150< td=""><td>S>150</td><td></td></s≤150<>	S>150					
		a≤0.03	N	C NC	NC	NC	NC					
1.5.11	d	0.03 <a≤0.05, b<="" td=""><td>)≤3 2</td><td>-</td><td>4</td><td>5</td><td>6</td><td>Minor</td></a≤0.05,>)≤3 2	-	4	5	6	Minor				
	↓ ^a	a>0.05 According to the criteria of <1.5.10>										
		Remark: Line	Remark: Linear scratch, dirt line should be regarded as linear									
		defect.										
		Maximum def										
		Suppose S=	The area	of A, the	criteria in A	&B is as bel	ow,					
	Polar bubble / Dent	S (cm ²) Φ (mm)	S≤4	4 <s≤12< td=""><td>12<\$≤50</td><td>50<s≤150< td=""><td>S>150</td><td></td></s≤150<></td></s≤12<>	12<\$≤50	50 <s≤150< td=""><td>S>150</td><td></td></s≤150<>	S>150					
4 5 40	b.	Φ≤0.15	NC	NC	NC	NC	NC					
1.5.12	n n	0.15<Φ≤0.25	1	2	2	3	3	Minor				
		0.25<Φ≤0.35	1	1	2	2	3					
	Ф= (a+b) / 2	Ф>0.35	0	0	0	0	0					
		Remark: Max	imum de	fect numb	er in 1cm² i	s 1.						
		Ignore the de	nt if it car	n't be seer	in positive	angle.						
1.5.13	Polarizer Stab	According to t	he criter	a of <1.5.	10>			Minor				
1.5.14	Polarizer Scratch	According to t	the criter	a of <1.5.	11>			Minor				
	FPC Pinhole		1			A.II	101					
4 5 45	→ Max W →	a a)	Allowed	•					
1.5.15	>	≤W/3			W	NC Natalia		Minor				
		>W/3		>	W	Not allo	owed					
	FPC Copper Residue	а)	Allowed	d Otv					
1.5.16	↓─────────────────────────────────────	≤W/3			W	NC		Minor				
1.5.15	≥ 4 b → a ⊗a	>W/3			W	Not allo		IVIII IOI				
	1 金美指 bb											
	FPC Impress /		Shape			Allowed Qty						
1.5.17	Crease	Moulage / Impr			NC			Minor				
		Crease with a s			Note allowed	<u> </u>		1				
1.5.18	Soldering defect	According to the criteria of IPC-A-610C										

Note (2): Suppose Length:Width = 4:3, The conversion between S & diagonal length is as below table,

S (cm ²)	Diagonal Length (Inch)
4	1.13
12	1.95
50	3.99
150	6.91

B.1.6 Inspection Criteria (Energized)

No	Defect Name & Illustration		Criteria							Class
1.6.1	Circular type when display (Not change along with voltage)	According to t	According to the criteria of <1.5.10>							Minor
	Circular type when	Suppose S= 7	Suppose S= The area of A, the criteria in a&b is as below,							
	display (Change along with voltage)	S (cm ²) Φ (mm)	S≤		4<\$≤		12 <s≤50< td=""><td>50<s≤150< td=""><td>S>150</td><td></td></s≤150<></td></s≤50<>	50 <s≤150< td=""><td>S>150</td><td></td></s≤150<>	S>150	
1.6.2		Ф≤0.30	N	С	NC	;	NC	NC	NC	Minor
		0.30<φ≤0.50	1		2		2	3	3	
	ם ו	0.50<Φ≤0.80	1		1		2	2	3	
		Ф>0.80	0	1	0		0	0	0	
	Φ = (a+b) / 2	Remark: Max	imum	defe	ect nui	mber	in 1cm ² is	s 1.		
1.6.3	Linear type when display (Not change along with voltage)	According to t								Minor
	Linear type when	Suppose S= 7		rea c	of A, th	ne crit	eria in a8	b is as belo	ow,	
	display (Change along with voltage)	S (c a&b ⊕ (mm)	:m²)	S≤4		S≤12	12 <s≤50< td=""><td></td><td></td><td></td></s≤50<>			
1.6.4	h	a≤0.05		NC		NC	NC	NC	NC	Minor
	a	0.05 <a≤0.10, b<="" td=""><td>)≤5</td><td>2</td><td></td><td>3</td><td>4</td><td>5</td><td>6</td><td></td></a≤0.10,>)≤5	2		3	4	5	6	
	▼	a>0.10						eria of <1.6.2>	>	
		Remark: Max								
	Pinhole	Suppose S= 7 S (cm²) Ф (mm)	ne a S≤		or A, tr 4<\$≤		eria in a8 12<\$≤50	50 <s≤150< td=""><td>S>150</td><td></td></s≤150<>	S>150	
1.6.5	, Ca	Φ≤0.10	N	?	NC	<u>:</u>	NC	NC	NC	Major
1.0.0		0.10<φ≤0.15	1		2		2	3	3	Major
	a o b	0.15<Φ≤0.25	1		_		2	2	3	
	b —	Ф>0.25	0)	0		0	0	0	
	$\Phi = (a+b) / 2$	Remark: Max	imum	defe	ect nui	mber	in 1cm ² is	s 1.		
1.6.6	Segment Distortion	More than 1/5	size	in sp	ec is	not al	lowed.			Major
1.6.7	Missing Segment (Row or column)	Not allowed.						Major		
1.6.8	Abnormal Display	Not allowed.	Not allowed.							Major
1.6.9	Display inhomogeneity / CR inhomogeneity	, and the second	According to the approved sample by both sides						Minor	
1.6.10	Too much current	Not allowed.								Major
1.6.11	No display	Not allowed.								Major
1.6.12	No backlight / flicking	Not allowed.								Major

B.2 Reliability Test

B.2.1 Standard Specifications for Reliability

B.2.1.1Test method

There should be no existing conspicuous failure of functions and appearance in LCD after the following tests.

NI.a	lta	Description
No	Item	Description
1	Low Temperature Operating	The sample should be allowed to stand at $(-20\pm2)^{\circ}$ °C for 96 Hours under driving condition.
2	High Temperature Operating	The sample should be allowed to stand at (70±2) [°] C for 96 Hours under driving condition.
3	Low Temperature Storage	The sample should be allowed to stand at (-30±3)°C for 96 Hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 24 hours
4	High Temperature Storage	The sample should be allowed to stand at (80±2) [°] C for 96Hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 24 hours
5	Moisture resistance	The sample should be allowed to stand at (40±2)°C, (95±2)%RH for 96Hours under no-load condition excluding the polarizer, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours
6	Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: T _{STL} * for 30 minutes -> normal temperature for 5 minutes -> T _{STH} * for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours

Note:

- T_{STL}: Lowest Storage Temperature.
- T_{STH}: Highest Storage Temperature.

B.2.1.2 Testing Conditions and Inspection Criteria:

For the final test, the testing sample must be stored at room temperature for 24 hours, after the tests listed above; Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Description
1	Current Consumption	The current consumption should be under double of initial test.
2	Contrast	The contrast must be larger than half of initial test.
3	Appearance	Appearance defects should not happen.

B.2.2 Life Time

Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±10°C), normal humidity (45±20%RH), and in area not exposed to direct sunlight.

B.3 Caution for Using

- 1. Recommended storage condition: 50~60%RH, 25+/-5°C;
- 2. Avoid direct sunlight. Avoid operating or storage under the temperature which exceeds the standard for a long time;
- 3. Avoid driving LCD with DC (Direct Current);
- 4. LCD was made of glass, please avoid any impact or pressure on surface;
- 5. If the skin contact with liquid crystal incautiously, wash with water for more than 15 minutes. If you feel uncomfortable, please see the doctor immediately;
- 6. It is prohibited to clean polarizer by ethanol or acetone. Clean polarizer by pure water is recommended;

- 7. The products should be used within 6 month. Otherwise, the ITO pad and FPC pad maybe be oxidized and cause poor contact, etc.;
- 8. ESD: TFT module or COG module is sensitive to ESD, effective action should be taken before you touch the products;
- 9. Avoid contacting the ITO pad by hand and pressing the surface of the LCD. Please take the both sides when you fetch the LCD.

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